

Title (en)

Method of autocatalytically tin-plating articles of copper or a copper alloy.

Title (de)

Verfahren zur autokatalytischen Verzinnung von Kupfer- und Kupferlegierungsgegenständen.

Title (fr)

Procédé pour l'étamage autocatalytique des objets en cuivre et alliages de cuivre.

Publication

**EP 0180265 A1 19860507 (EN)**

Application

**EP 85201585 A 19851002**

Priority

NL 8403033 A 19841005

Abstract (en)

Improvement of an electroless tin-plating method of articles of copper or of a copper alloy with a strongly alkaline solution which contains at least 0.20 mol/litre of bivalent tin ions and at least 1 mol/litre of alkali hydroxide at a temperature between 60 and 95 DEG C. The improvement consists of a pre-treatment with an acid solution of a bivalent tin salt and a complex former for Cu<+><+> and/or Sn<+><+> ions with which a layer of copper at the surface is exchanged for tin. The complex former preferably is thiourea.

IPC 1-7

**C23C 18/46**

IPC 8 full level

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CPC (source: EP KR)

**C23C 18/31** (2013.01 - EP); **C23C 18/54** (2013.01 - KR)

Citation (search report)

- [A] US 2369620 A 19450213 - SULLIVAN JOHN D, et al
- [AD] GB 2039534 A 19800813 - PHILIPS NV

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EP0851041A1; EP0460786A1; EP0848084A4; US5334240A; US5143544A; US5169692A; US5296268A; US5173109A; GB2271578A; GB2271578B

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